

**ANTICORROSIVE MATERIAL FOR SEMICONDUCTOR FABRICATION**

**Patent number:** JP10004083  
**Publication date:** 1998-01-06  
**Inventor:** ITOU YUMIKO; AIDA HIROSHI  
**Applicant:** KYOCERA CORP  
**Classification:**  
- **international:** H01L21/3065; C01B21/06; H01L21/205; H01L21/68  
- **european:**  
**Application number:** JP19960155798 19960617  
**Priority number(s):**

**Abstract of JP10004083**

**PROBLEM TO BE SOLVED:** To provide an anticorrosive material having a higher corrosion resistance than SiO<sub>2</sub> , Al<sub>2</sub>O<sub>3</sub> , AlN, etc.

**SOLUTION:** A part of a product to be exposed to a fluoric corrosive gas such as SF<sub>6</sub> , CF<sub>4</sub> , CHF<sub>3</sub> , CIF<sub>3</sub> and HF or its plasma is made from a compd. thin film or single crystal. The product is e.g. a Si wafer clamp ring, upper electrode shield ring, or inner wall of a plasma treating apparatus, etching apparatus, etc., for the semiconductor fabrication. The compd. is an oxide, nitride, carbide or fluoride of 3a elements on the periodic table, e.g. Sc, La, Ce, Eu and Dy.

---

Data supplied from the **esp@cenet** database - Patent Abstracts of Japan